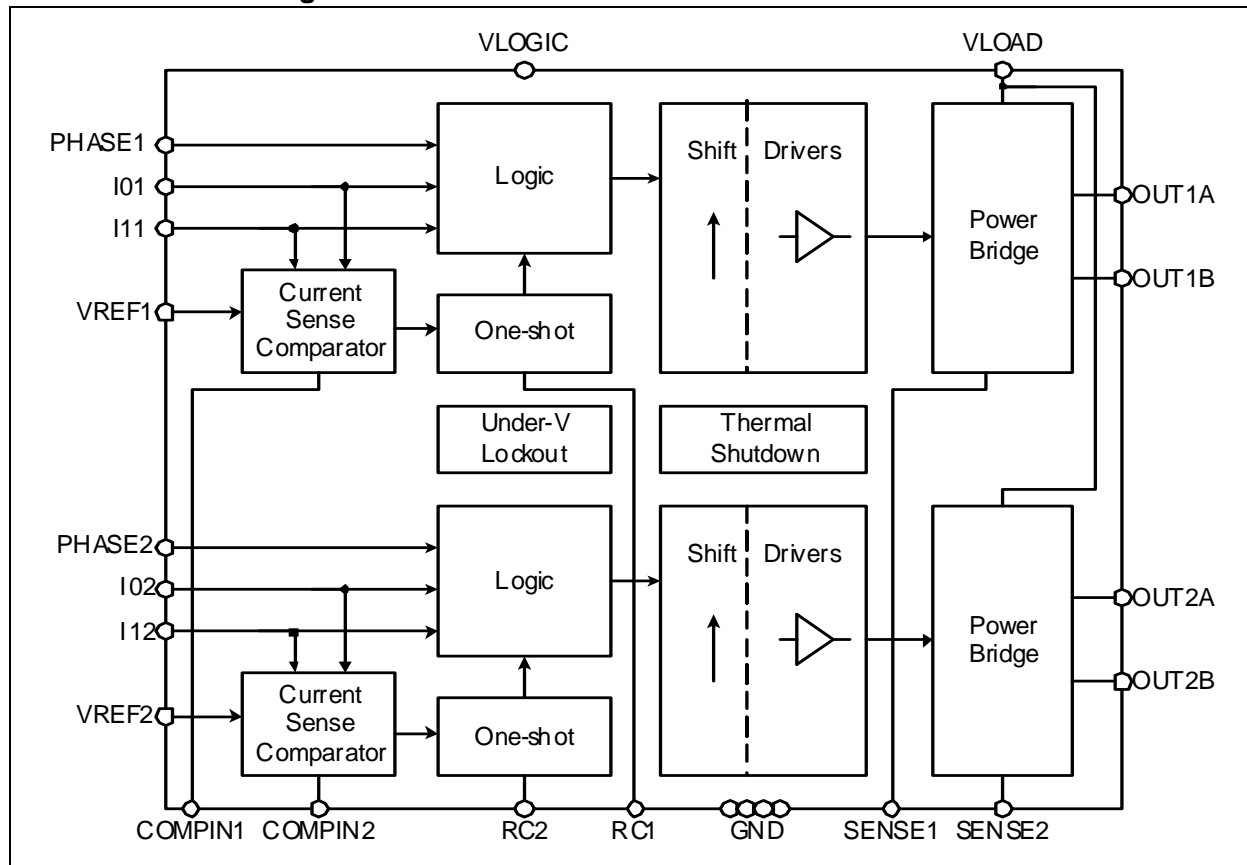
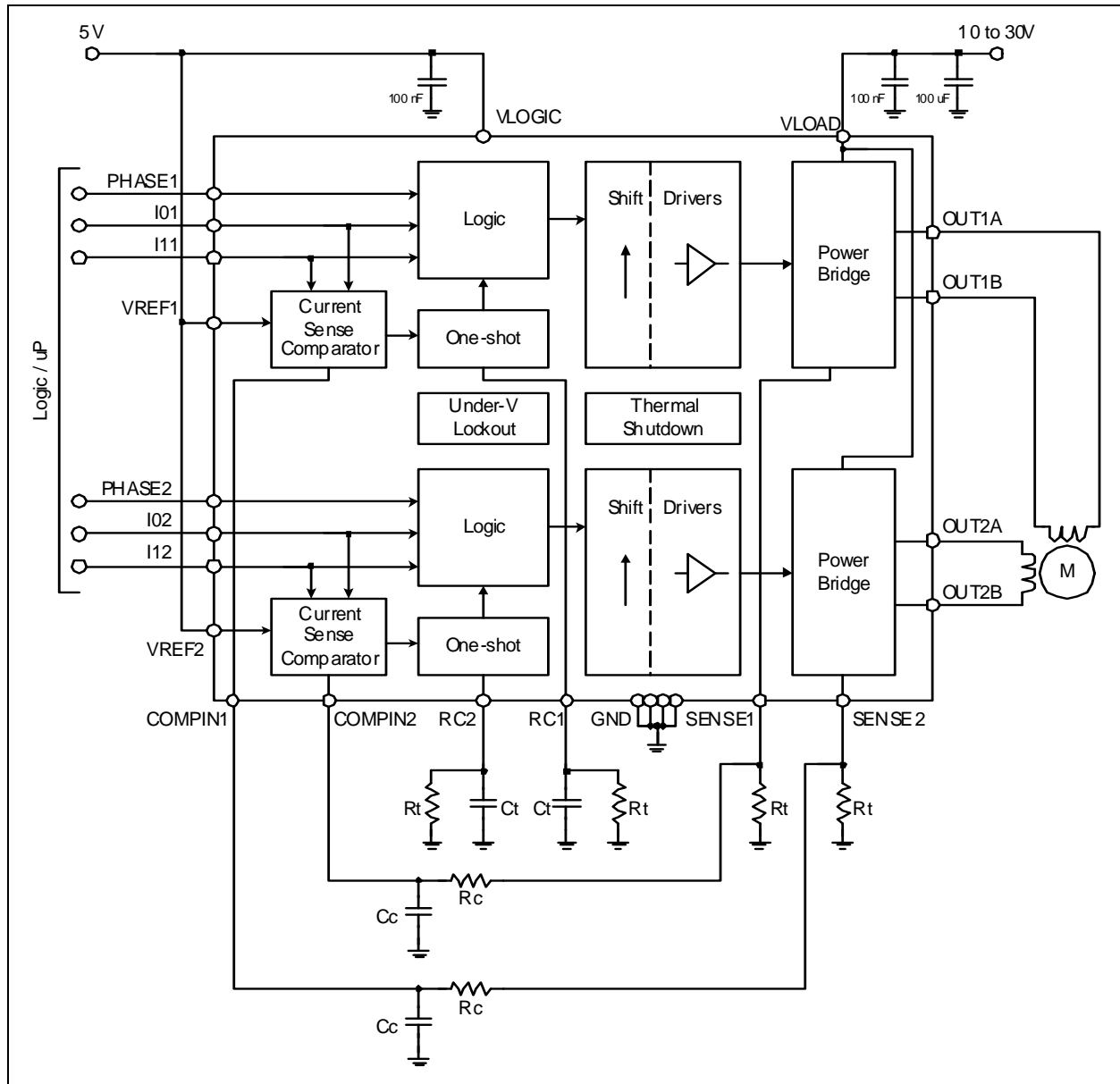


MTS2916A

Functional Block Diagram



Typical Application



MTS2916A

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Logic Supply Voltage (V_{LOGIC})	-0.3 to +5.5V
Load Supply Voltage (V_{LOAD})	-0.3 to +40.0V
Logic Input Voltage Range (V_{IN})	-0.3 to $V_{\text{LOGIC}} + 0.3\text{V}$
V_{REF} Voltage Range (V_{REF})	-0.3 to +10.0V
Output Current (Peak)	$\pm 1\text{A}$
Output Current (Continuous)	$\pm 0.75\text{A}$
Sense Output Voltage	-0.3V to 1.5V
Junction Temperature (T_{J})	-20°C to +150°C
Operating Temperature Range (T_{OPR})	-20°C to +85°C
Storage Temperature Range (T_{STG})	-55°C to +150°C

† **Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all limits are established for $V_{\text{LOGIC}} = 4.5\text{V}$ to 5.5V , $V_{\text{LOAD}} = 30\text{V}$, $V_{\text{REF}} = 5\text{V}$, $T_{\text{A}} = 25^{\circ}\text{C}$

Parameters	Sym	Min	Typ	Max	Units	Conditions
DC Characteristics						
Logic Supply Voltage	V_{LOGIC}	4.5	5.0	5.5	V	
Load Supply Voltage	V_{LOAD}	10	30	40	V	
Logic Supply Current	I_{VLOGIC}	—	0.8	1.0	mA	
V_{REF} Voltage Range	V_{REF}	1.5	5.0	7.0	V	
Driver Supply Current	$I_{\text{VLOAD_ON}}$	—	0.55	1.0	mA	Both Bridges ON, No Load
	$I_{\text{VLOAD_OFF}}$	—	0.55	1.0	mA	Both Bridges Off
Control Logic Input Current ($V_{\text{IN}} = 0\text{V}$)	I_{IN}	—	—	-70	μA	I01,I11,I02,I12,PHASE1,PHASE2, (Note 1)
Logic Low Input Voltage	V_{IL}	—	—	0.8	V	I01,I11,I02,I12,PHASE1,PHASE2
Logic High Input Voltage	V_{IH}	2.4	—	—	V	I01,I11,I02,I12,PHASE1,PHASE2
Current Limit Threshold Ratio ($V_{\text{REF}} \div V_{\text{SENSE}}$)	$V_{\text{REF_VSENSE}}$	9.5	10	10.5	—	I0=L,I1=L
		13.5	15	16.5	—	I0=H,I1=L
		25.5	30	34.5	—	I0=L,I1=H
Driver Output Saturation Voltage $V_{\text{CE(SAT)}}$	V_{ONN} (Low Side)	—	0.55	0.65	V	(Sink) IOUT = +500 mA
		—	0.90	1.00	V	(Sink) IOUT = +750 mA
	V_{ONP} (High Side)	—	1.05	1.40	V	(Source) IOUT = -500 mA
		—	1.85	2.10	V	(Source) IOUT = -750 mA
Clamp Diode Forward Voltage (Note 2)	$V_{\text{F_NDIODE}}$	—	0.95	1.30	V	$I_{\text{F}} = 750\text{ mA}$
	$V_{\text{F_PDIODE}}$	—	1.00	1.30	V	$I_{\text{F}} = 750\text{ mA}$
Driver Output Leakage Current	I_{LEAK}	—	—	-50	μA	$V_{\text{OUT}} = 0\text{V}$
		—	—	50	μA	$V_{\text{OUT}} = V_{\text{LOAD}}$
Thermal Shutdown Temperature	$T_{\text{J_SHDN}}$	—	170	—	$^{\circ}\text{C}$	
AC Characteristics						
Cut-off Time (one-shot pulse)	T_{OFF}	—	50	58	μs	$R_{\text{s}}=1\Omega, R_{\text{c}}=1\text{k}\Omega, C_{\text{c}}=820\text{pF}, R_{\text{t}}=56\text{k}\Omega, C_{\text{t}}=820\text{pF}$
Turn-off Delay	T_{D}	—	1.5	10	μs	
			—	—		

Note 1: $V_{\text{IN}} = 5.0\text{V}$ input current given by internal pull-up to Logic Supply.

2: Clamp/Freewheel diode is the intrinsic body-drain diode of the NMOS and PMOS transistors.

TEMPERATURE SPECIFICATIONS

Parameters	Sym	Min	Typ	Max	Units	Conditions
Recommended Temperature Ranges						
Junction Temperature Range	T_J	-20		+125	°C	
Operating Temperature Range	T_A	-20		+70	°C	
Thermal Package Resistance						
Thermal Resistance, SOP-24	θ_{JA} θ_{JC}	— —	76 16	— —	°C/W	EIA/JEDEC JESD51-10

MTS2916A

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 2-1](#).

TABLE 2-1: MTS2916A PIN FUNCTION TABLE

Pin No. SOP-24	Type	Name	Function
1	Input	I02	Output 2 Current Selection Bit 0
2	Input	I12	Output 2 Current Selection Bit 1
3	Input	PHASE2	Output 2 Phase
4	Input	VREF2	Output 2 Current Reference
5	Input	RC2	Output 2 RC Time Constant
6	Power	GND	Negative Logic Supply (Ground)
7	Power	GND	Negative Logic Supply (Ground)
8	Power	VLOGIC	Positive Logic Supply Voltage
9	Input	RC1	Output 1 RC Time Constant
10	Input	VREF1	Output 1 Current Reference
11	Input	PHASE1	Output 1 Phase
12	Input	I11	Output 1 Current Selection Bit 1
13	Input	I01	Output 1 Current Selection Bit 0
14	Output	OUT1B	Output 1 'B' Side of Motor Winding
15	Input	COMPIN1	Current Sense Comparator Input for Output 1
16	Input	SENSE1	Current Sense for Output 1
17	Output	OUT1A	Output 1 'A' Side of Motor Winding
18	Power	GND	Negative Logic Supply (Ground)
19	Power	GND	Negative Logic Supply (Ground)
20	Output	OUT2A	Output 2 'A' Side of Motor Winding
21	Input	SENSE2	Current Sense for Output 2
22	Input	COMPIN2	Current Sense Comparator Input for Output 2
23	Output	OUT2B	Output 2 'B' Side of Motor Winding
24	Power	VLOAD	Positive Load Supply Voltage

2.1 Ground Terminal (GND)

Logic supply ground. Only the driver current flows out of this pin; there is no high current. Minimize voltage drops between this pin and the logic inputs.

2.2 Logic Supply Voltage (VLOGIC)

Connect VLOGIC to the logic source voltage. Decouple the supply with a 0.1 μ F ceramic capacitor mounted close to the VLOGIC and GND terminals.

2.3 Load Supply Voltage (VLOAD)

Connect VLOAD to the motor positive voltage supply. The motor current is supplied through this pin and the selected output transistors.

2.4 Current Detection Selection (I01, I02, I11, I12)

Comparator input for current threshold detection. The voltage across the sense resistor is fed back to this input through the low pass filter RcCc. The power transistors are disabled when the sense voltage exceeds the reference voltage of the selected comparator. When this occurs the current decays for a time set by RtCt ($T_{OFF} = 1.1 \text{ RtCt}$).

2.5 Current Flow Direction Selection (PHASE1, PHASE2)

Logic input to select the direction of current flow through the load. A "HIGH" logic signal level causes load current to flow from OUTxA to OUTxB. A "LOW" logic level causes load current to flow from OUTxB to OUTxA.

2.6 Current Sense Reference (VREF1, VREF2)

Reference voltage for current sense comparator. Determines the level of output current detection together with sensing resistor and inputs I0x, I1x.

2.7 Current Sense Input (SENSE1, SENSE2)

Connection to lower sources of output stage for insertion of current sense resistor.

2.8 Current Sense Comparator Input (COMPIN1, COMPIN2)

Current sense comparator input.

2.9 Output Stage OFF Time (RC1, RC2)

A parallel RtCt network connected to this pin sets the OFF time of the power transistors. The pulse generator is a monostable triggered by the output of the current sense comparator.

2.10 Output Stage (OUT1A, OUT2A, OUT1B, OUT2B)

Output connection to "A" side and "B" side of motor windings.

3.0 FUNCTIONAL DESCRIPTION

The circuit is designed to drive the two windings of a bipolar stepper motor and can be divided in two identical channels (channel 1 and channel 2) and protection circuitry for over temperature and undervoltage. The functionality of a channel and protection circuitry is presented on next sections.

3.1 Power Bridge Operation

Each motor winding is driven by an H-type bridge consisting of two N and two P transistors that allow the current to flow in both winding directions depending on the value of the PHASE signal (Table 3-1). The H-bridge can be set in 5 configurations that are related to the digital inputs PHASE, I0 and I1, and to the current sensed. These configurations are given in Table 3-2.

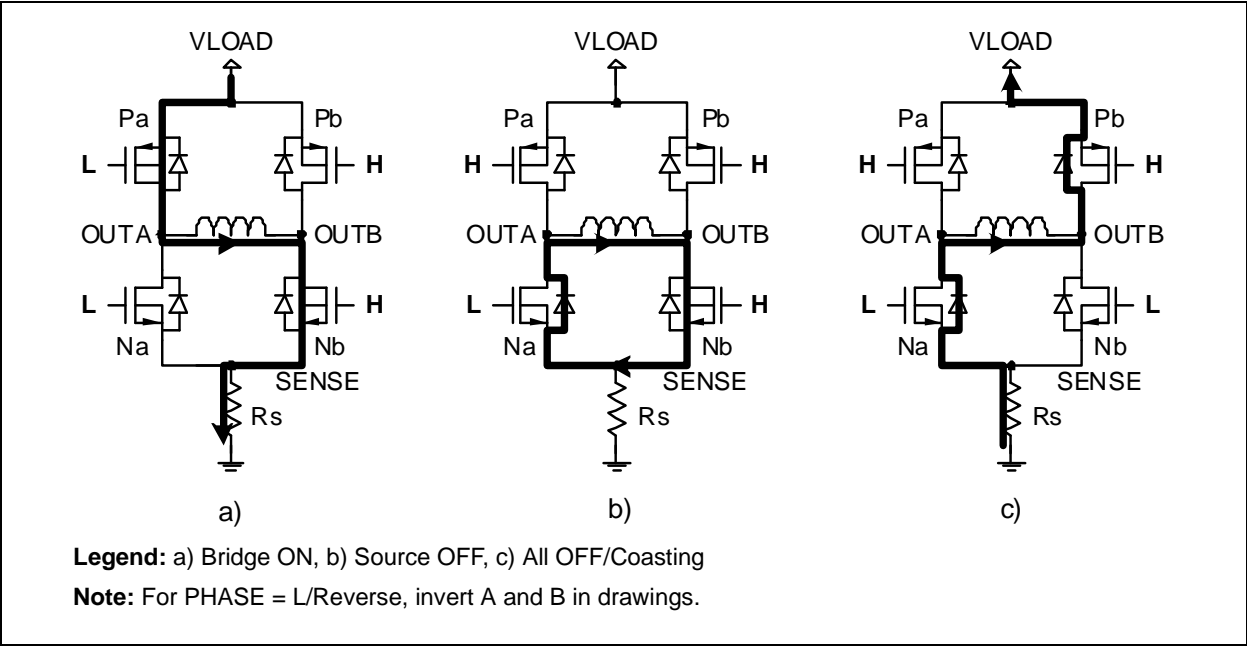


FIGURE 3-1: Power Bridge Control (PHASE = H/Forward)

TABLE 3-1: CURRENT DIRECTION CONTROL

PHASE	Output Current
L	Current flows from OUTxB to OUTxA
H	Current flows from OUTxA to OUTxB

TABLE 3-2: POWER BRIDGE GATE CONTROL TRUTH TABLE

I0I1	PHASE	overi	T _{OFF}	Case/Mode	gna	gpa	gnb	gpb
00/01/10	1	0	0	Forward ON	L	L	H	H
00/01/10	1	x	1	Forward OFF	L	H	H	H
00/01/10	0	0	0	Reverse ON	H	H	L	L
00/01/10	0	x	1	Reverse OFF	H	H	L	H
11	x	x	x	No Current/Coasting	L	H	L	H

Legend: Bold = Active MOS Transistors, Overi = Overcurrent flag, T_{OFF} = Channel T_{OFF} State Flag

3.2 PWM Current Control

The current level in each motor winding is controlled by a PWM circuit with a fixed T_{OFF} time. The load current flowing in the winding is sensed through an external sensing resistor R_s connected between the power bridge's source pin SENSE (sources of transistors Na and Nb) and GND.

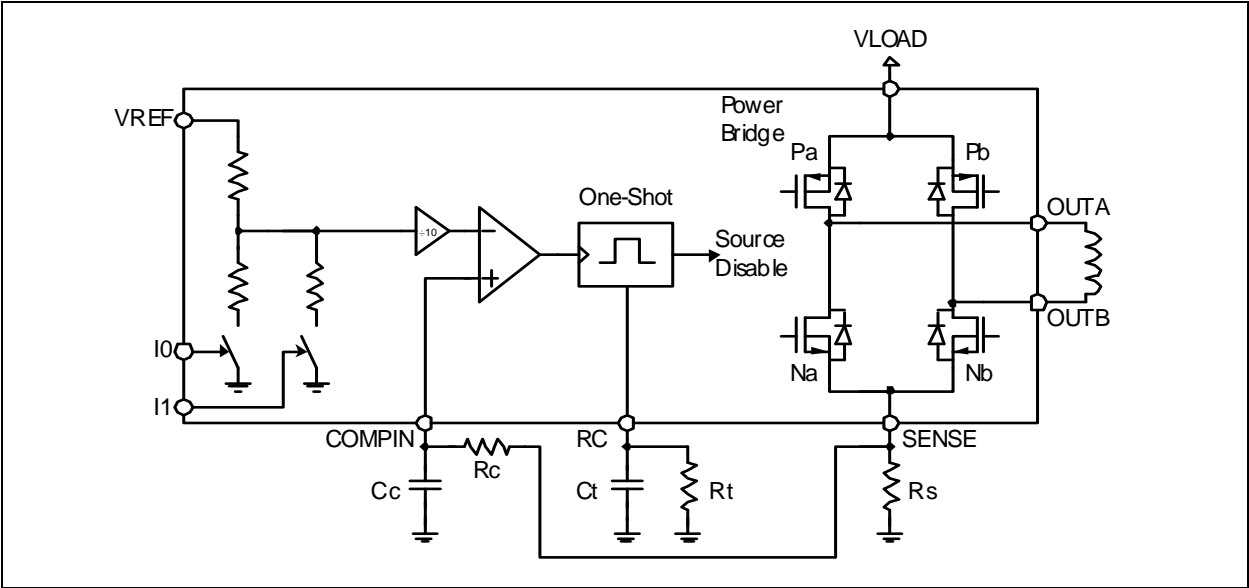


FIGURE 3-2: PWM Current Control Circuit Principle (Channel 1 Shown)

The voltage across R_s is compared to a fraction of the reference voltage VREF, chosen with the logic input bits I0 and I1 (Table 3-3). The power bridge and thus the load current can also be switched off completely when both logic inputs are high. Note that any logic input left unconnected will be treated as a high level (pull-up resistor).

EQUATION 3-1:

$$I_{MAX} = \frac{V_{REF}}{10 * R_s}$$

The maximum trip current for regulation, given for I0 I1 = 00 is calculated in Equation 3-1.

TABLE 3-3: CURRENT LEVEL CONTROL TRUTH TABLE

I0	I1	Comp. Trip Voltage	Output Current
0	0	Vtrip = 1/10*Vref	I _{max} = Vref/10RS
1	0	Vtrip = 1/15*Vref	2/3*I _{max} = Vref/15RS
0	1	Vtrip = 1/30*Vref	1/3*I _{max} = Vref/30RS
1	1	x	0 (no current)

When the maximum allowed current is reached, the bridge source is turned off during a fixed period T_{OFF} (typically 50us) given by a non-retriggerable pulse generator and the external timing components R_t (20k-100 kΩ range) and C_t (100 pF-1000 pF range):

During T_{OFF}, the winding current decreases. When the driver is re-enabled, the winding current increases again until it reaches the threshold, and the cycle repeats itself maintaining the load current at the desired level.

t_{off} = 1.1*(R_t*C_t)

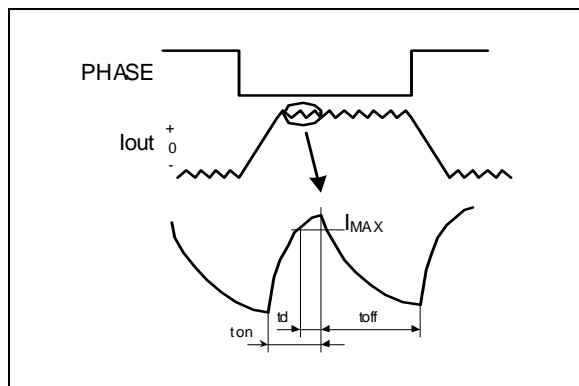


FIGURE 3-3: PWM Output Current Waveform

3.3 Circuit Protection

A thermal protection circuitry turns off all drivers when the junction temperature exceeds a safe operating limit of 170°C (typ.). This protects the devices from failure due to excessive heating. Despite this thermal protection, output short circuits are not permitted. The output drivers are re-enabled once junction temperature has dropped below 145°C (typ.).

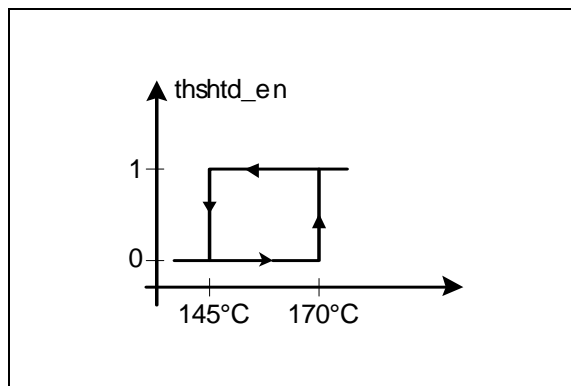


FIGURE 3-4: Thermal Shutdown Output vs. Temperature Showing Hysteresis

An undervoltage lockout circuit protects the MTS2916A from potential shoot-through currents when the load supply voltage is applied prior to the logic supply voltage. The power bridge and all outputs are disabled if VLOGIC is smaller than 4V.

With this protection feature, the circuit will withstand any order of turn-on or turn-off of the supply voltages VLOGIC and VLOAD. Normal dV/dt values are assumed.

4.0 APPLICATION CIRCUITS & ISSUES

4.1 Typical Application

The MTS2916A circuit with external components for a typical application is shown in Figure 4-1. Typical passive component values are: $R_s = 1\Omega$, $R_c = 1k\Omega$, $C_c = 820pF$, $R_t = 56k\Omega$ and $C_t = 820pF$.

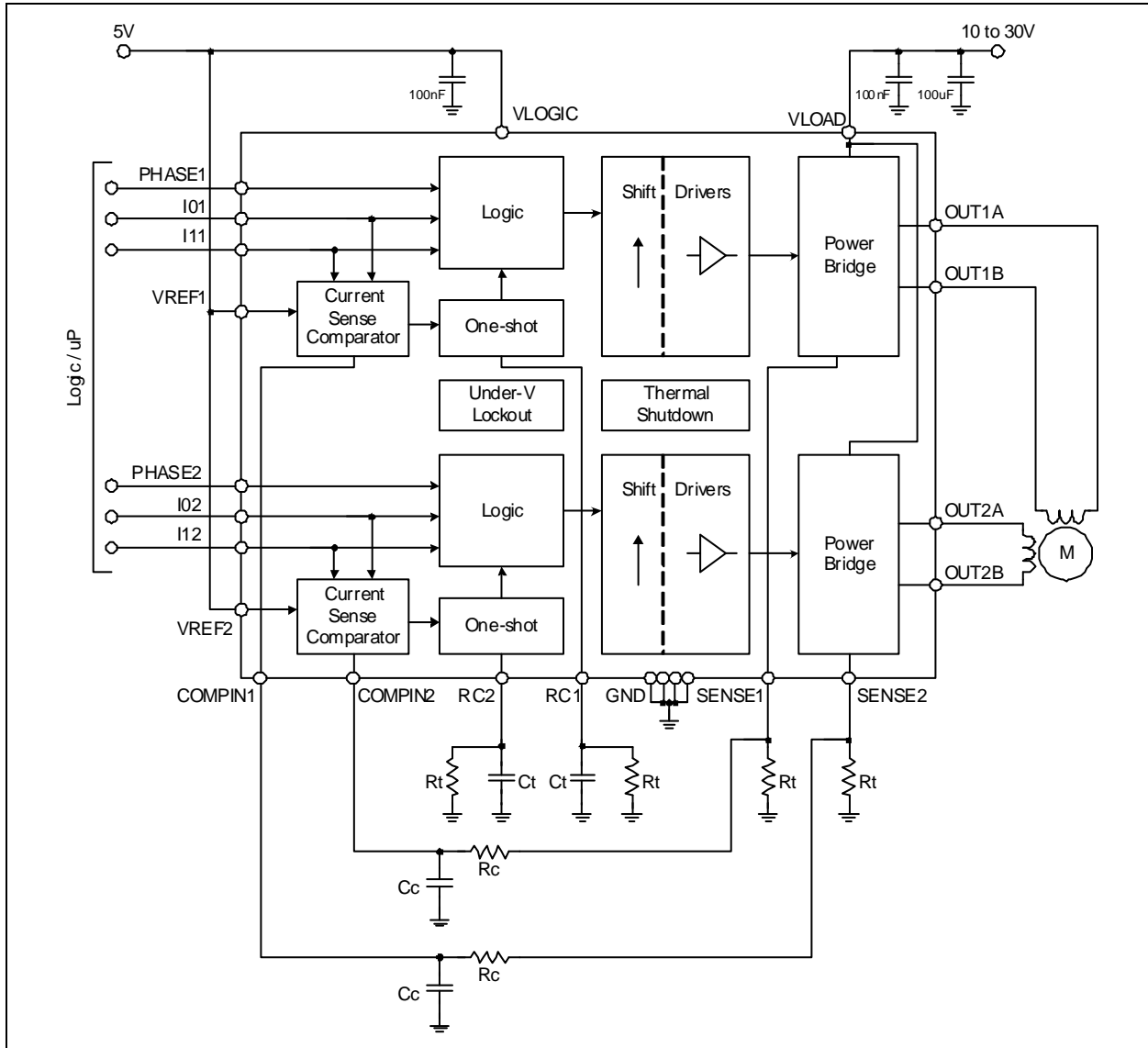


FIGURE 4-1: Typical Application Circuit

During PWM operation, when the output stage is turned-on, large voltage peaks might appear across R_s , which can wrongly trigger the input comparator. To avoid an unstable current control, an external R_cC_c filter should be used that delays the comparator action. Depending on load type, many applications will not require this filter (SENSE connected to COMPIN).

MTS2916A

4.2 Stepping Examples

The MTS2916A allows to control a motor in full-step, half-step, modified half-step and microstepping mode, as shown in Figure 4-2.

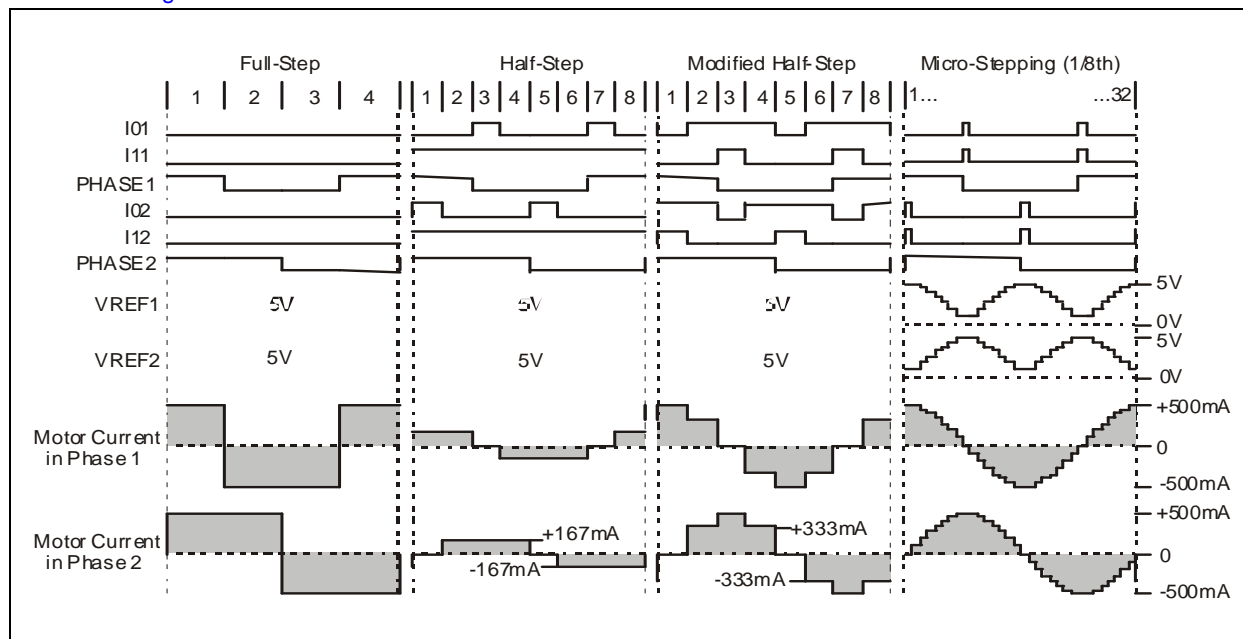


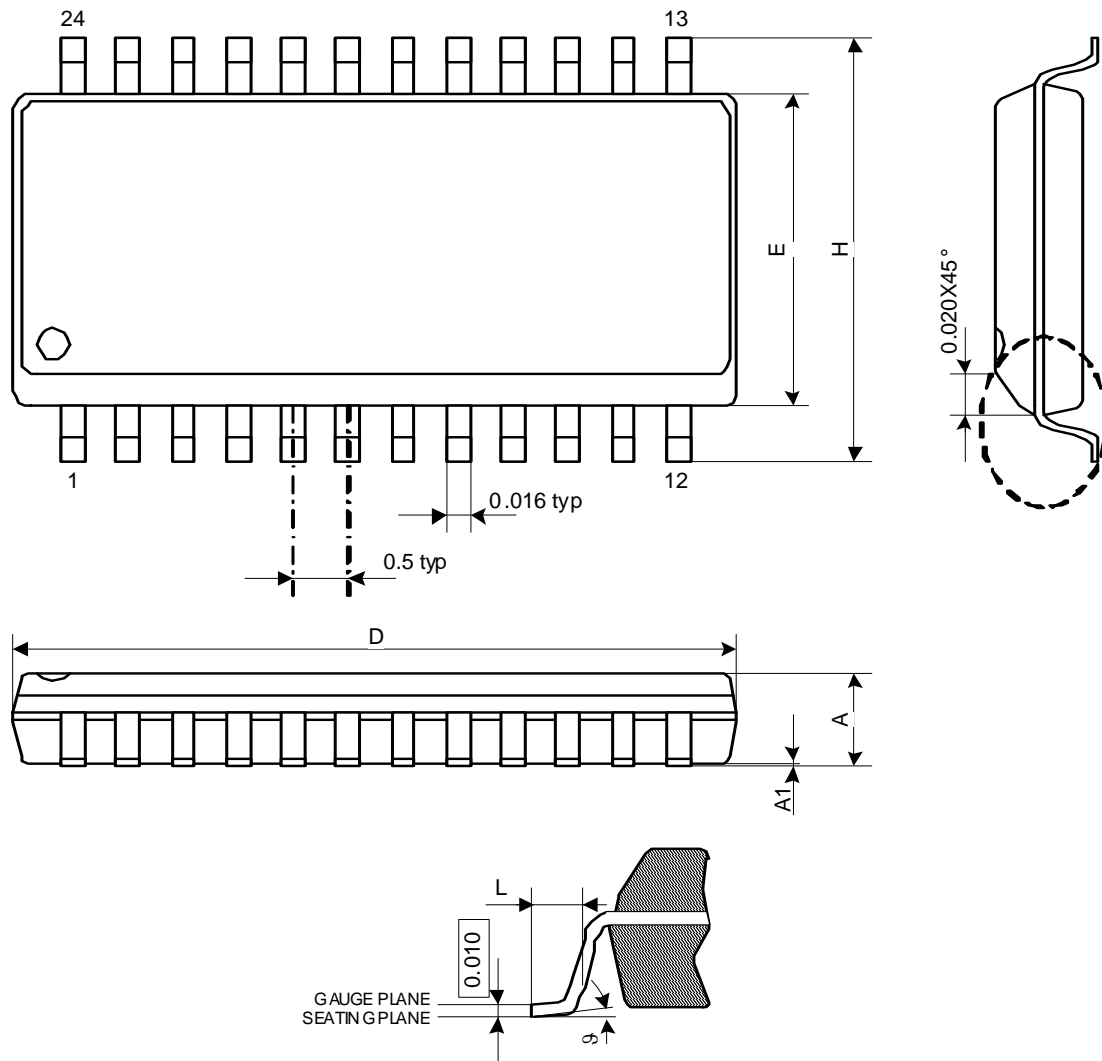
FIGURE 4-2: Examples of Stepping Modes Achievable with Typical Application Circuit

4.3 PCB Design Guidelines

Unused inputs should be connected to fixed voltage levels in order to get the highest noise immunity. Typical PCB layout guidelines for power application should be followed. These include separate power ground planes, supply decoupling capacitors close to the IC, short connections and use of maximized copper areas to improve thermal dissipation.

5.0 MECHANICAL DIMENSIONS

SOP 24L Package Outline



Symbol	Minimum	Typical	Maximum	Unit
A	—	—	2.642 (0.104)	mm (inch)
A1	0.102 (0.004)	—	—	mm (inch)
D	15.545 (0.612)	15.697 (0.618)	15.850 (0.624)	mm (inch)
E	7.417 (0.292)	7.518 (0.296)	7.595 (0.299)	mm (inch)
H	10.287 (0.405)	10.464 (0.412)	10.643 (0.419)	mm (inch)
L	0.533 (0.021)	0.787 (0.031)	1.041 (0.041)	mm (inch)
J	0	4	8	°

Note 1: JEDEC outline: M0-119 AA

- 2:** Dimensions "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions and gate burrs should not exceed 0.25mm (0.010inch) per side.
- 3:** Dimensions "E" does not include inter-lead flash, or protrusions. Inter-lead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.

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NOTES:

APPENDIX A: REVISION HISTORY

Revision A (September 2010)

- Original Release of this Document.

MTS2916A

NOTES:

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ISBN: 978-1-60932-536-7

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